

specification and all the claims are included as Appendix A. In making these amendments, no new matter is entered.

TITLE OF THE INVENTION:

Please amend the title of the invention to read "MULTILAYER ELECTRONIC DEVICES WITH VIA COMPONENTS."

IN THE SPECIFICATION:

Please amend the specification of the above-referenced application to appear as below. Such amendments are requested merely to modify inadvertent typographical errors in the specification and do not add any new matter to the specification.

Please replace the first full paragraph on page 14 with the following:

A1  
"In still a further preferred embodiment of the present invention, Figures 6-13 show the use of a blind via 148 to house electrically connected passive components 114 within an integrated passive device 150. In such an embodiment, the vias 148 contain various passive components 114 as discussed above which serve in addition to their electrical functions as connections between other of the passive components comprising the device 150. In this manner, the footprint of an IPD may be reduced while providing greater flexibility in its design layout."

Please replace the first full paragraph on page 15 with the following:

A2  
"With the basic construction of the device's skeletal frame 150 completed, as can be seen in Figure 9, the manufacturer is now able to form the additional resistive/conductive patterns 158 required on an outer surface of the device and band terminate the edges to provide terminations 160 for such device. The methods of making such patterns 158 and terminations 160 are varied but generally known in the art. They form no particular aspect of the present invention and therefore will not be explained in detail."

Please replace the first full paragraph on page 16 by the following:

A3  
"In order to ensure both the electrical and physical stability of the passive component 114, the vias 148 may be filled with an insulating epoxy 166 or other similar material to partially encase the passive component 114 and hold it in place. As

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discussed above and as seen in Figure 13, if the conductor patterns have been formed either by thin-film plating or thick-film printing, the electrical connection to the upper conductor 164 may then be formed by filling in the remaining portion of the via 148 either with a conductor or a solder paste 118 and either cure or reflow it, respectively."

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IN THE CLAIMS:

Please amend claims 19, 23 and 25 of the above-identified application to appear as below. The amendments regarding such claims do not add any new matter to the subject application.

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19. (Amended) A multi-layer electrical device comprising:

a first device layer with a first series of resistive/conductive patterns thereon;

a second device layer with a plurality of via drilled therethrough;

a unitary device body formed by the bonded union of the first and second device layers, wherein said via correspond to a respective capture pad in said first series of resistive/conductive patterns;

a second series of resistive/conductive patterns on an outer layer of said unitary body;

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a plurality of terminations on said unitary body for electrical connection between other electronic devices and components of said device;

individual passive components with first and second opposing electrical terminations, wherein each said individual passive component is vertically mounted into a selected of said plurality of via and wherein one of said first and second opposing electrical terminations is bonded to the respective capture pad for said selected of said plurality of via;

multiple portions of a non-conductive material respectively substantially filling the space between each of said individual passive components and the surrounding via, wherein said non-conductive material partially encases each said individual passive component to hold it in place while leaving one of said first and second opposing electrical terminations exposed and prevents shorting between respective first and second opposing electrical terminations; and